Dual Complementary General Purpose Transistor

The NST847BPDP6T5G device is a spin-off of our popular SOT-23/SOT-323/SOT-563 three-leaded device. It is designed for general purpose amplifier applications and is housed in the SOT-963 six-leaded surface mount package. By putting two discrete devices in one package, this device is ideal for low-power surface mount applications where board space is at a premium.

Features

- h_{FE}, 200-450
- Low $V_{CE(sat)}$, $\leq 0.3 \text{ V}$
- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- This is a Pb-Free Device

MAXIMUM RATINGS

Rating		Symbol	Value	Unit
Collector - Emitter Voltage		V_{CEO}	45	Vdc
Collector - Base Voltage		V _{CBO}	50	Vdc
Emitter – Base Voltage		V _{EBO}	6.0	Vdc
Collector Current - Continuous		I _C	100	mAdc
Electrostatic Discharge	HBM MM	ESD Class	2 B	

THERMAL CHARACTERISTICS

Characteristic (Single Heated)	Symbol	Max	Unit
Total Device Dissipation T _A = 25°C Derate above 25°C (Note 1)	P _D	240 1.9	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	520	°C/W
Total Device Dissipation T _A = 25°C Derate above 25°C (Note 2)	P _D	280 2.2	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	446	°C/W
Characteristic (Dual Heated) (Note 3)	Symbol	Max	Unit
Total Device Dissipation T _A = 25°C Derate above 25°C (Note 1)	P _D	350 2.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	357	°C/W
Total Device Dissipation T _A = 25°C Derate above 25°C (Note 2)	P _D	420 3.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	297	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	–55 to +150	°C

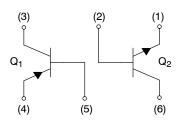
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. FR-4 @ 100 mm², 1 oz. copper traces, still air. 2. FR-4 @ 500 mm², 1 oz. copper traces, still air.
- 3. Dual heated values assume total power is sum of two equally powered channels



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NST847BPDP6T5G*

*Q1 PNP Q2 NPN



CASE 527AD

MARKING DIAGRAM



= Device Code = Date Code

ORDERING INFORMATION

Device	Package	Shipping [†]
NST847BPDP6T5G	SOT-963 (Pb-Free)	8000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS				I.		
Collector – Emitter Breakdown Voltage ($I_C = 1.0 \text{ mA}, I_B = 0$) ($I_C = -1.0 \text{ mA}, I_B = 0$)	(NPN) (PNP)	V _{(BR)CEO}	45 -45	_ _	_ _	V
Collector – Base Breakdown Voltage ($I_C = 10 \mu A, I_E = 0$) ($I_C = -10 \mu A, I_E = 0$)	(NPN) (PNP)	V _{(BR)CBO}	50 –50	- -		V
Collector – Emitter Breakdown Voltage ($I_C = 10 \mu A$) ($I_C = -10 \mu A$)	(NPN) (PNP)	V _{(BR)CES}	50 –50	- -	_ _	٧
Emitter – Base Breakdown Voltage $ (I_E=1.0~\mu\text{A},~I_C=0) \\ (I_E=-1.0~\mu\text{A},~I_C=0) $	(NPN) (PNP)	V _{(BR)EBO}	6.0 -5.0	- -	_ _	V
Collector Cutoff Current (V _{CB} = 30 V) (V _{CB} = 30 V, T _A = 150°C) (V _{CB} = -30 V) (V _{CB} = -30 V, T _A = 150°C)	(NPN) (NPN) (PNP) (PNP)	Ісво	- - -	- - - -	15 5.0 -15 -4.0	nA μA nA μA
ON CHARACTERISTICS (Note 4) DC Current Gain		h				1
$(I_C = 2.0 \text{ mA}, V_{CE} = 5.0 \text{ V})$	(NPN)	h _{FE}	200	290	450	_
$(I_C = -2.0 \text{ mA}, V_{CE} = -5.0 \text{ V})$	(PNP)		220	290	475	
Collector – Emitter Saturation Voltage ($I_C = 10 \text{ mA}, I_B = 0.5 \text{ mA}$) ($I_C = 100 \text{ mA}, I_B = 5.0 \text{ mA}$)	(NPN)	V _{CE(sat)}	-	-	0.25 0.60	V
$(I_C = -10 \text{ mA}, I_B = -0.5 \text{ mA})$ $(I_C = -100 \text{ mA}, I_B = -5.0 \text{ mA})$	(PNP)		- -	- -	-0.30 -0.70	
Base – Emitter Saturation Voltage (I_C = 10 mA, I_B = 0.5 mA) (I_C = 100 mA, I_B = 5.0 mA)	(NPN)	V _{BE(sat)}	-	0.70 0.90	- -	V
$(I_C = -10 \text{ mA}, I_B = -0.5 \text{ mA})$ $(I_C = -100 \text{ mA}, I_B = -5.0 \text{ mA})$	(PNP)		- -	-0.70 -0.90	_ _	
Base – Emitter On Voltage (I_C = 2.0 mA, V_{CE} = 5.0 V) (I_C = 10 mA, V_{CE} = 5.0 V)	(NPN)	V _{BE(on)}	0.58	0.66 -	0.70 0.77	V
$(I_C = -2.0 \text{ mA}, V_{CE} = -5.0 \text{ V})$ $(I_C = -10 \text{ mA}, V_{CE} = -5.0 \text{ V})$	(PNP)		-0.60 -	- -	-0.75 -0.82	
SMALL-SIGNAL CHARACTERISTICS			•	-	•	•
Current-Gain – Bandwidth Product $(I_C = 10 \text{ mA}, V_{CE} = 5.0 \text{ V}, f = 100 \text{ MHz})$	(NPN)	f _T	100	-	_	MHz
$(I_C = -10 \text{ mA}, V_{CE} = -5.0 \text{ V}, f = 100 \text{ MHz})$	(PNP)		100	-	-	
Output Capacitance (V _{CB} = 10 V, f = 1.0 MHz)	(NPN)	C _{ob}	-	-	4.5	pF
$(V_{CB} = -10 \text{ V}, f = 1.0 \text{ MHz})$	(PNP)		-	-	4.5	
Noise Figure (I _C = 0.2 mA, V _{CE} = 5.0 V, R _S = 2 k Ω , f = 1 kHz, BW = 200 Hz)	(NPN)	NF	-	-	10	dB
				ı	1	1

^{4.} Pulse Test: Pulse Width ≤ 300 μs; Duty Cycle ≤ 2.0%.

NPN TRANSISTOR

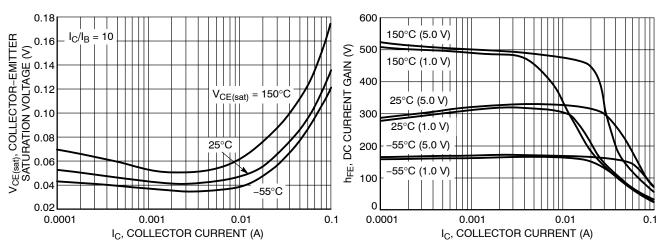


Figure 1. Collector Emitter Saturation Voltage vs. Collector Current

Figure 2. DC Current Gain vs. Collector Current

NPN TRANSISTOR

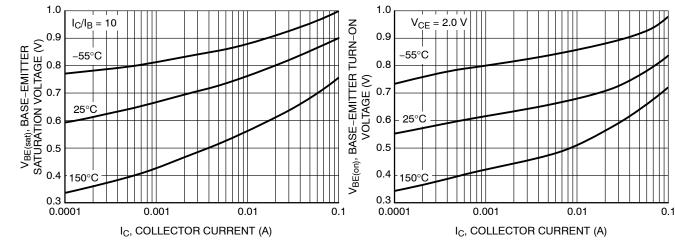


Figure 3. Base Emitter Saturation Voltage vs.
Collector Current

Figure 4. Base Emitter Turn-On Voltage vs.
Collector Current

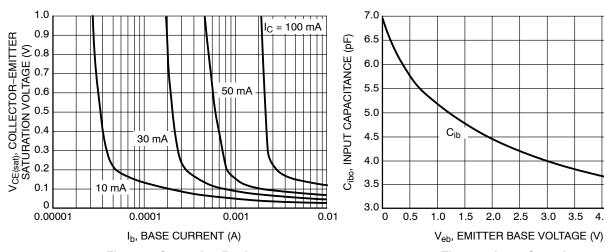


Figure 5. Saturation Region

Figure 6. Input Capacitance

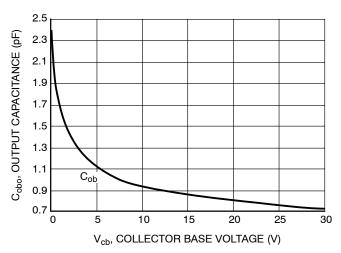


Figure 7. Output Capacitance

PNP TRANSISTOR

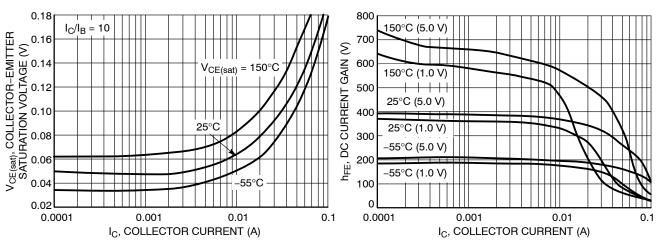


Figure 8. Collector Emitter Saturation Voltage vs. Collector Current

Figure 9. DC Current Gain vs. Collector Current

PNP TRANSISTOR

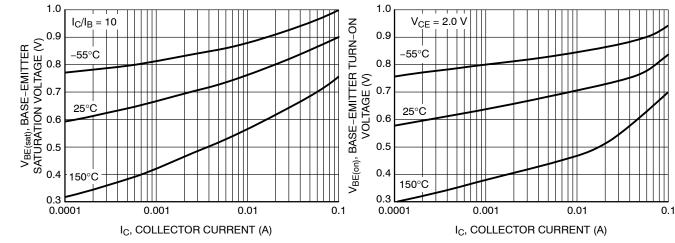
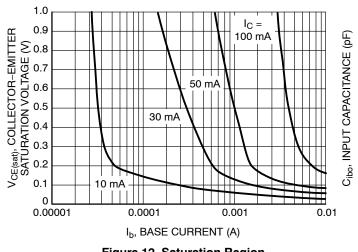


Figure 10. Base Emitter Saturation Voltage vs. **Collector Current**

Figure 11. Base Emitter Turn-On Voltage vs. **Collector Current**



6 \mathbf{C}_{ib} 5 4 3 0 1.0 2.0 4.0 5.0 V_{eb}, EMITTER BASE VOLTAGE (V)

10

9

8

7

Figure 12. Saturation Region

Figure 13. Input Capacitance

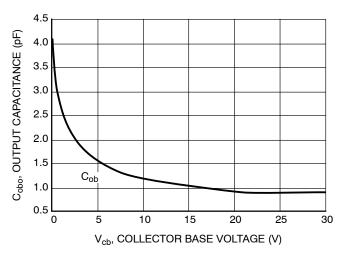
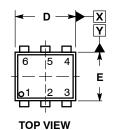
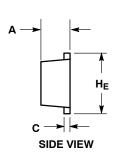


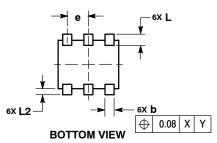
Figure 14. Output Capacitance

PACKAGE DIMENSIONS

SOT-963 CASE 527AD **ISSUE E**





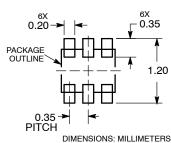


NOTES

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS				
DIM	MIN	MIN NOM			
Α	0.34	0.37	0.40		
b	0.10	0.15	0.20		
С	0.07	0.12	0.17		
D	0.95	1.00	1.05		
E	0.75	0.80	0.85		
е	0.35 BSC				
HE	0.95	1.00	1.05		
L	0.19 REF				
L2	0.05	0.10 0.1			

RECOMMENDED MOUNTING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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